September, 2013

SJ-FET

RTF80R850S/RTP80R850S/RTT80R850S/ RTU80R850S 800V N-Channel MOSFET

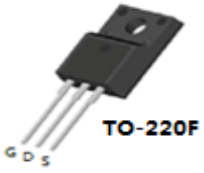
Description

SSMOS-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.
This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy.
SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.

Features

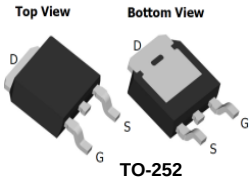
- Multi-Epi process SJ-FET
- 850V @TJ = 150 ℃
- Typ. RDS(on) = 0.8Ω (TO-220F)
- Ultra Low Gate Charge (typ. Qg = 9.5nC)
- 100% avalanche tested

RTF80R850S



RTP80R850S

RTT80R850S



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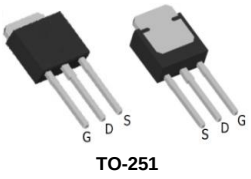
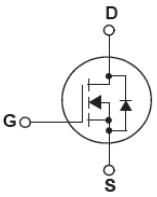




Absolute Maximum Ratings

Symbol	Parameter	RTF80R850S	RTP80R850S	Unit
V_{DSS}	Drain-Source Voltage	800		V
I_D	Drain Current -Continuous (TC = 25℃) -Continuous (TC = 100℃)	6.6* 4.2*		A
I_{DM}	Drain Current - Pulsed (Note 1)	20*		A
V_{GSS}	Gate-Source voltage	±30		V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	86		mJ
I_{AR}	Avalanche Current (Note 1)	1.7		A
E_{AR}	Repetitive Avalanche Energy (Note 1)	0.2		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	15		V/ns
dVds/dt	Drain Source voltage slope (Vds=640V)	50		V/ns
P_D	Power Dissipation (TC = 25℃)	63	28	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150		℃
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300		℃

* Drain current limited by maximum junction temperature. Maximum duty cycle D=0.75.

Thermal Characteristics

Symbol	Parameter	RTF80R850S	RTP80R850S	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	2.0	4.5	℃/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	-	℃/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	80	℃/W

Electrical Characteristics TC = 25℃ unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = 250μA, T_J = 25℃	800	-	-	V
		V_{GS} = 0V, I_D = 250μA, T_J = 150℃	-	850	-	V
ΔBV_{DSS} / ΔT_J	Breakdown Voltage Temperature Coefficient	I_D = 250μA, Referenced to 25℃	-	0.6	-	V/℃
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 800V, V_{GS} = 0V -T_J = 150℃	-	- 10	1 -	μA μA
I_{GSSF}	Gate-Body Leakage Current, Forward	V_{GS} = 30V, V_{DS} = 0V	-	-	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -30V, V_{DS} = 0V	-	-	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	2.5	3.5	4.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS} = 10V, I_D = 3.5A (TO-220F/TO-220)	-	0.8	0.9	Ω
		V_{GS} = 10V, I_D = 3.5A (TO-251/TO-252)	-	0.85	0.93	Ω
g_{FS}	Forward Transconductance	V_{DS} = 40V, I_D = 7A	-	6	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 25V, V_{GS} = 0V, f = 1MHz	-	380	-	pF
C_{oss}	Output Capacitance		-	115	-	pF
C_{rss}	Reverse Transfer Capacitance		-	9	-	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 400V, I_D = 3.5A, R_G = 25Ω(Note 4)	-	23	-	ns
t_r	Turn-On Rise Time		-	19	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	44	-	ns
t_f	Turn-Off Fall Time		-	18	-	ns
Q_g	Total Gate Charge	V_{DS} = 450V, I_D = 3.5A, V_{GS} = 10V (Note 4)	-	9.5	-	nC
Q_{gs}	Gate-Source Charge		-	1.9	-	nC
Q_{gd}	Gate-Drain Charge		-	4.5	-	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		-	-	7	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		-	-	20	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0V, I_S = 7A	-	0.9	1.5	V
t_{rr}	Reverse Recovery Time	V_R = 400V, V_{GS} = 0V, I_F = 7A, dI_F/dt =100A/μs	-	550	-	ns
Q_{rr}	Reverse Recovery Charge		-	4.8	-	μC
I_{rrm}	Peak reverse recovery Current		-	15.5	-	A

NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. I_{AS}=1.7A, VDD=50V, Starting TJ=25 ℃
3. I_{SD}≤ID, di/dt ≤ 200A/us, V_{DD} ≤ BV_{DSS}, Starting TJ = 25 ℃
4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

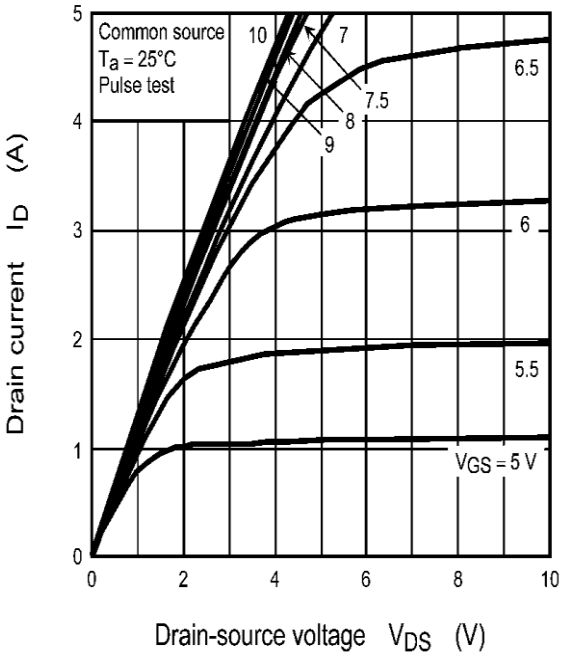


Figure 1: On-Region Characteristics@25°C

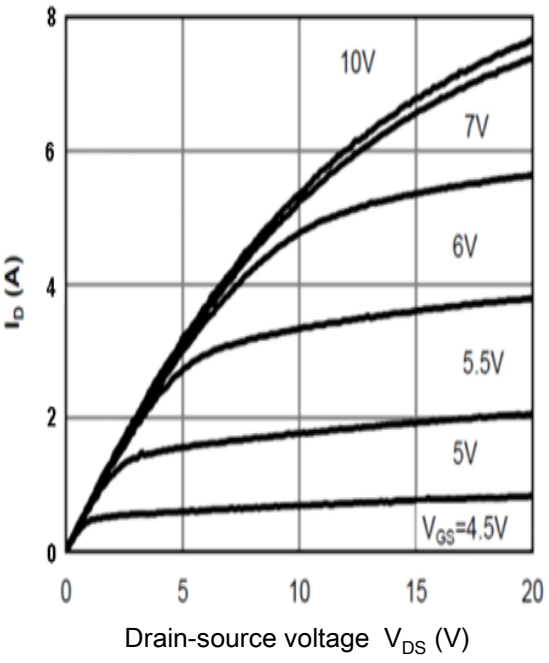


Figure 2: On-Region Characteristics@125°C

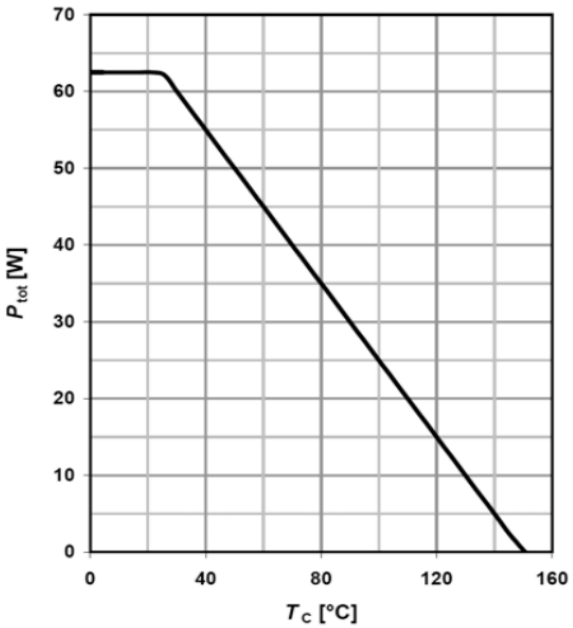


Figure 3:Power Dissipation
TO-220, TO-252, TO-251

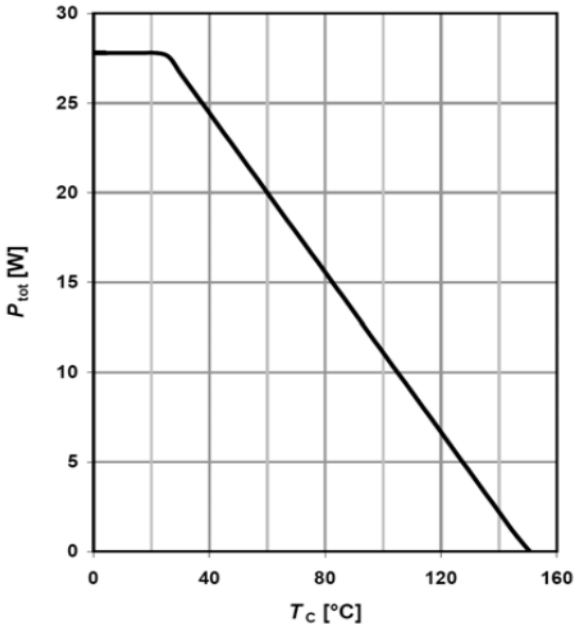


Figure 4 : Power dissipation
TO-220FullPAK

Typical Performance Characteristics

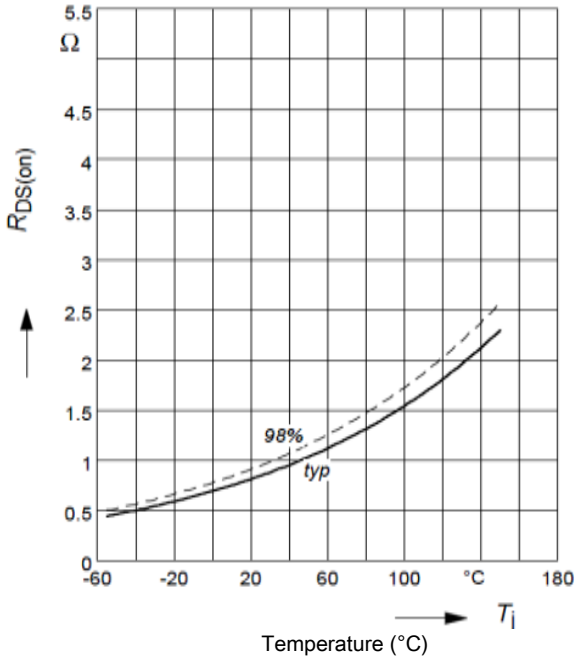


Figure 5: On-Resistance vs. Junction Temperature
TO-220FullPAK

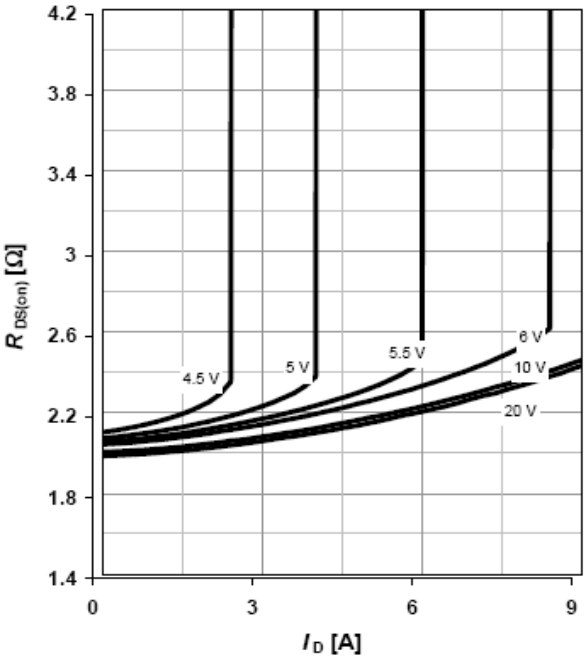


Figure 6: On-Resistance vs. Drain Current, Tj=150°C

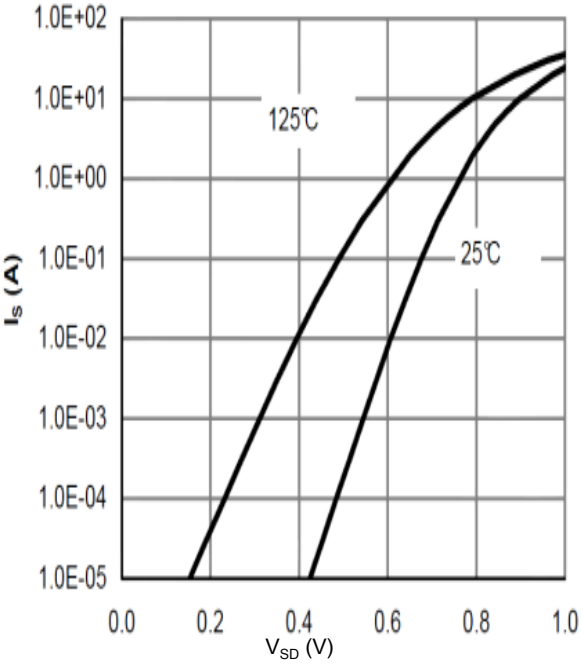


Figure 7: Body-Diode Characteristics

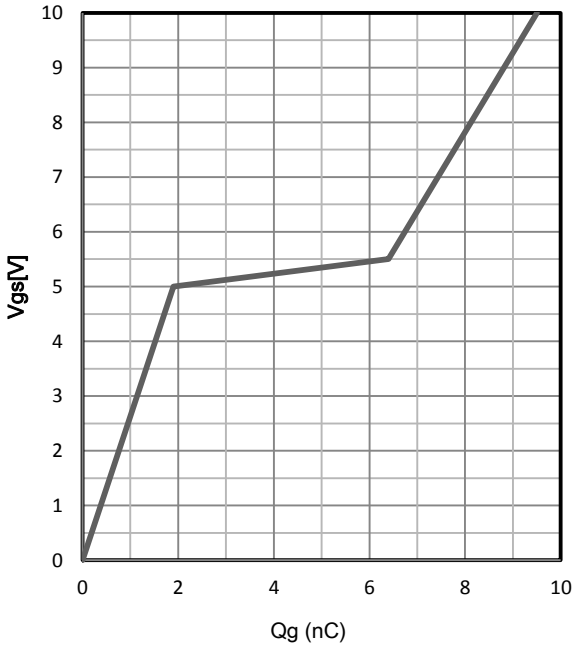


Figure 8: Gate-Charge Characteristics

Typical Performance Characteristics

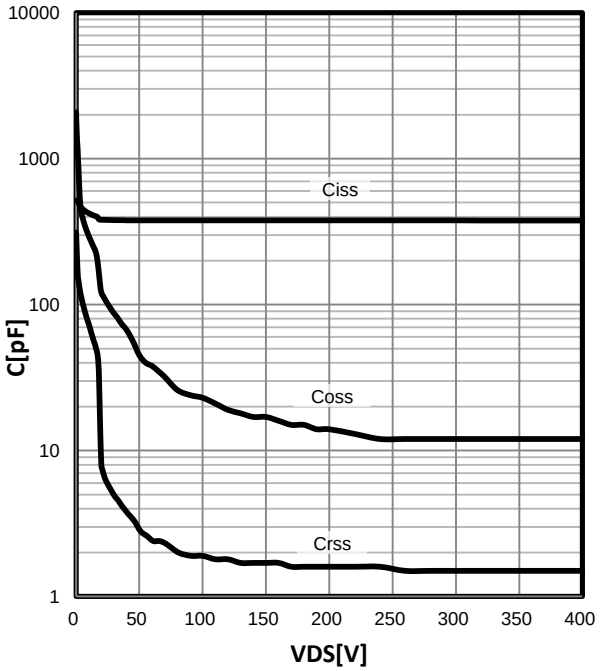


Figure 9: Capacitance Characteristics

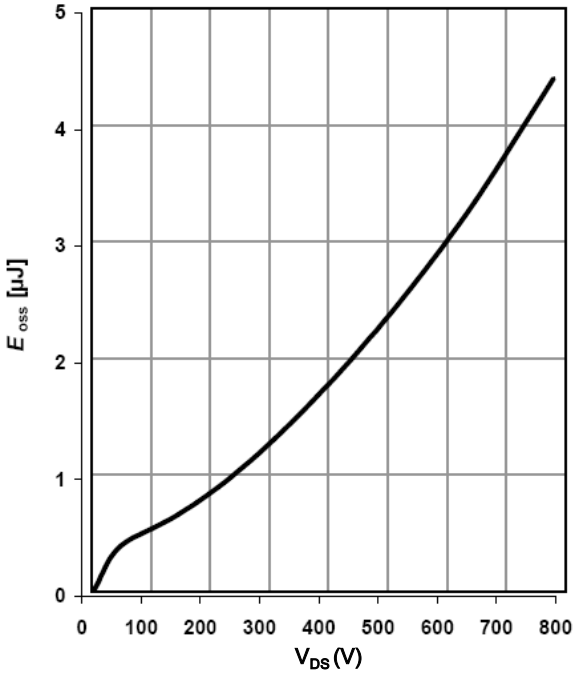


Figure 10: C_{oss} stored Energy

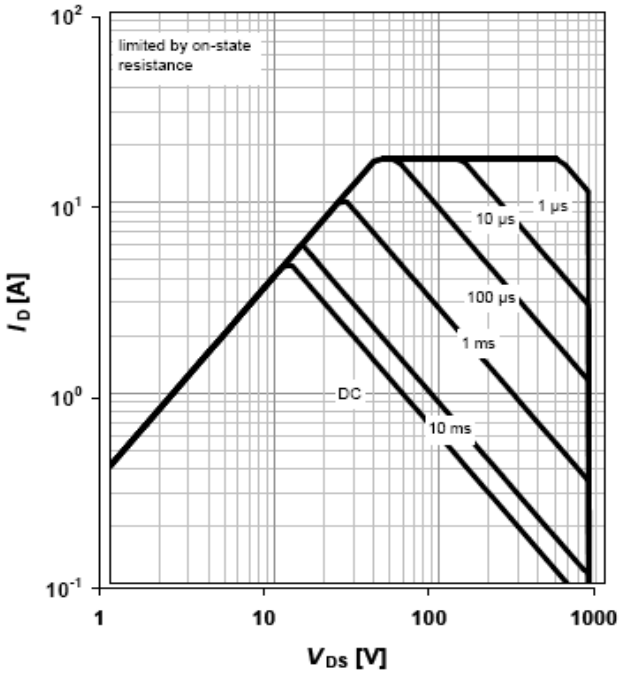


Figure 11: Maximum Forward Biased Safe Operating Area Tc=25°C (TO-220, TO-252, TO-251)

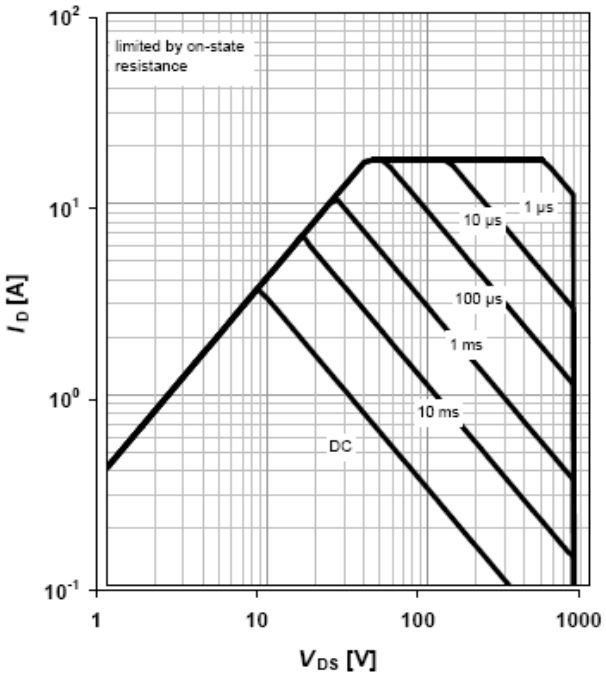


Figure 12: Maximum Forward Biased Safe Operating Area Tc=25°C (TO-220 FullPAK)

Typical Performance Characteristics

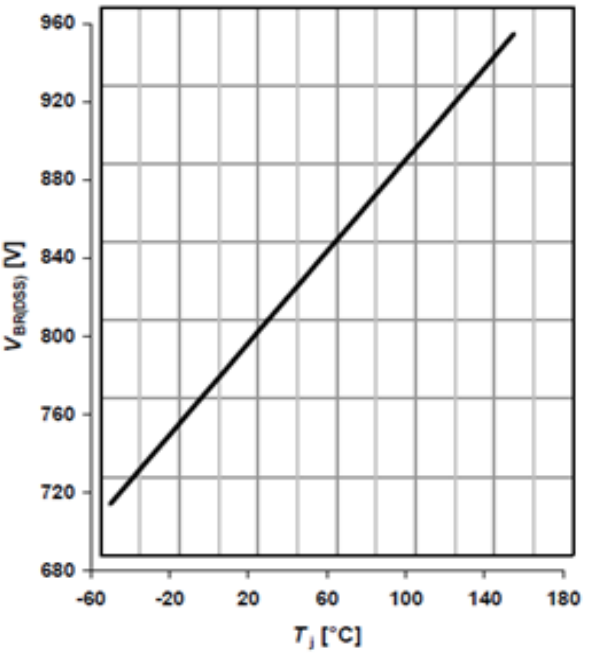


Figure 13: Break Down vs. Junction Temperature

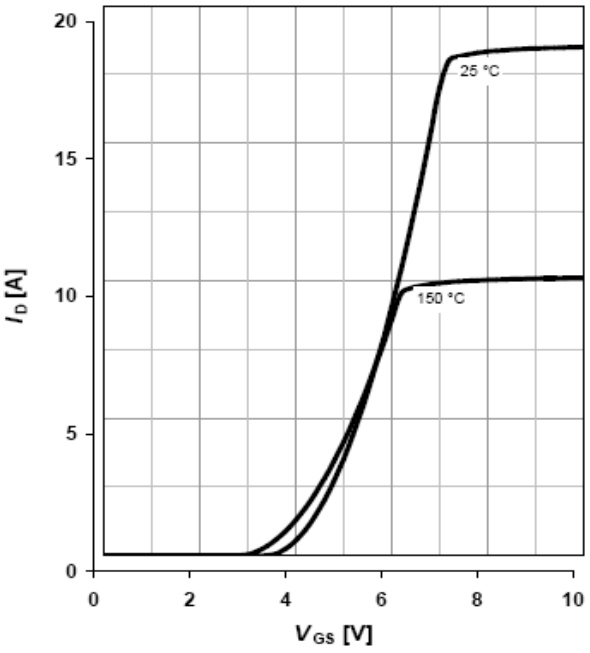


Figure 14: Typical transfer characteristics

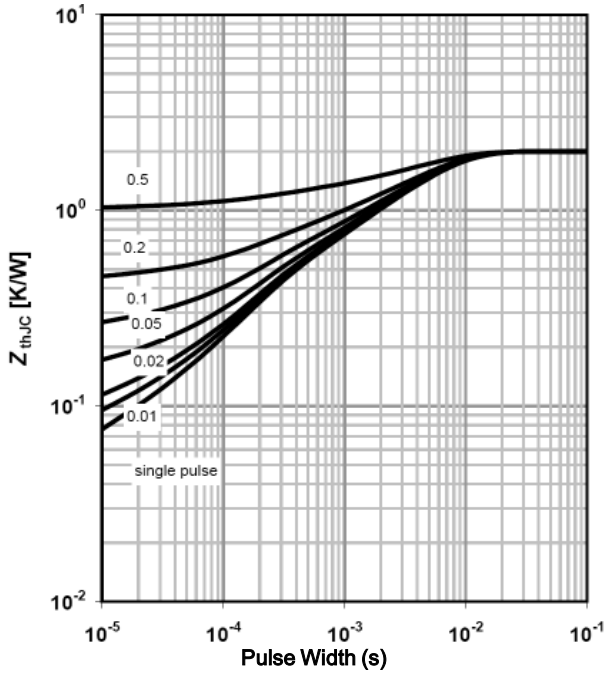


Figure 15: Maximum Transient Thermal Impedance
TO-220, TO-252, TO-251

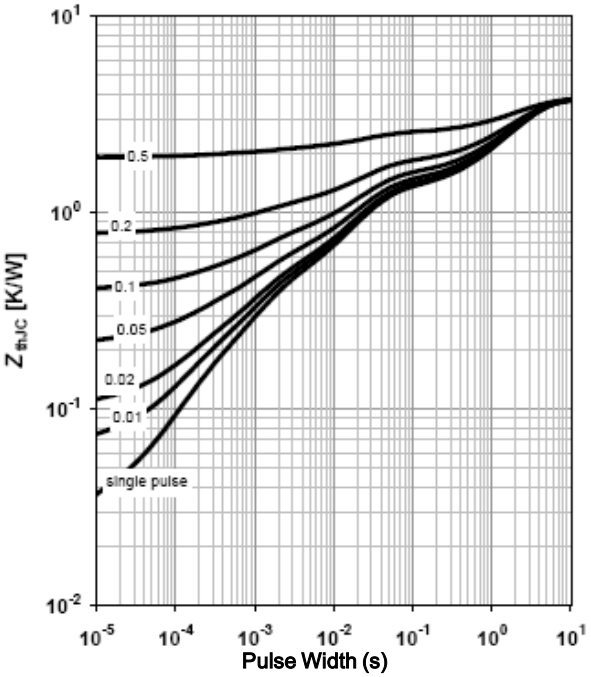


Figure 16: Maximum Transient Thermal Impedance
TO-220 FULLPAK

Typical Performance Characteristics

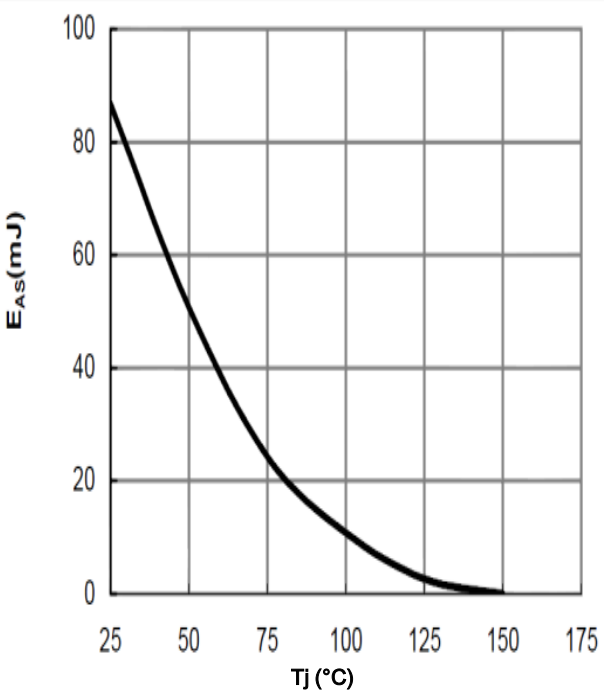
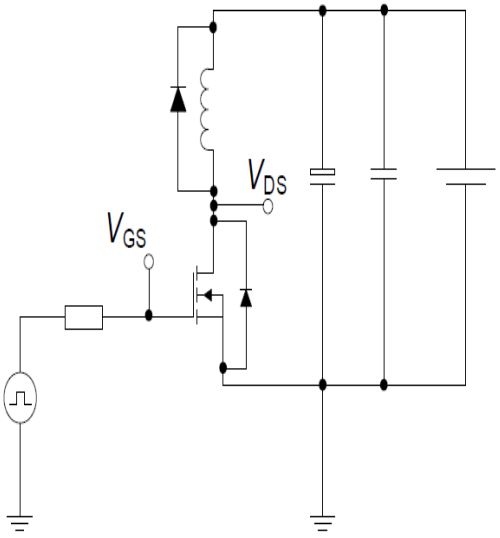


Figure 17: Avalanche energy

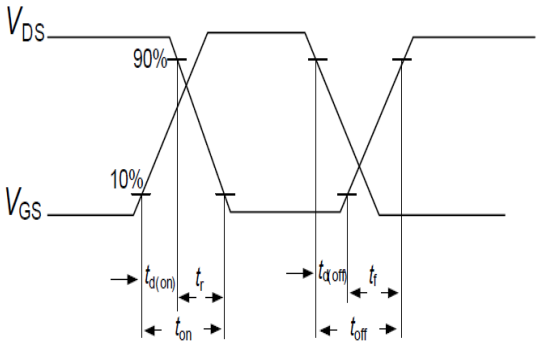
Test circuits

Switching times test circuit and waveform for inductive load

Switching times test circuit for inductive load

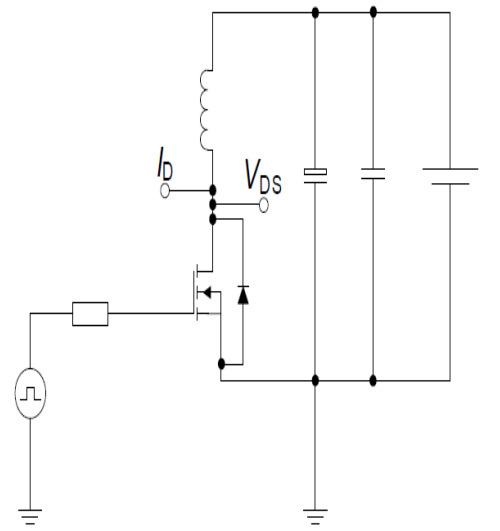


Switching time waveform

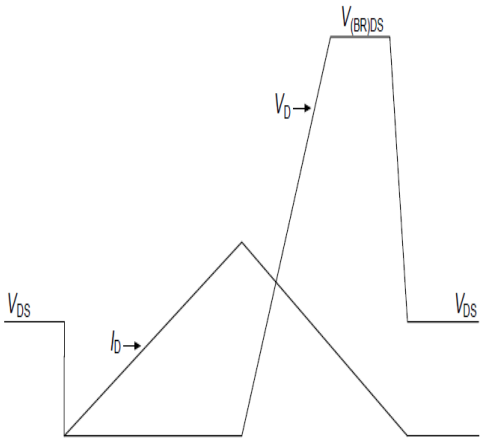


Unclamped inductive load test circuit and waveform

Unclamped inductive load test circuit



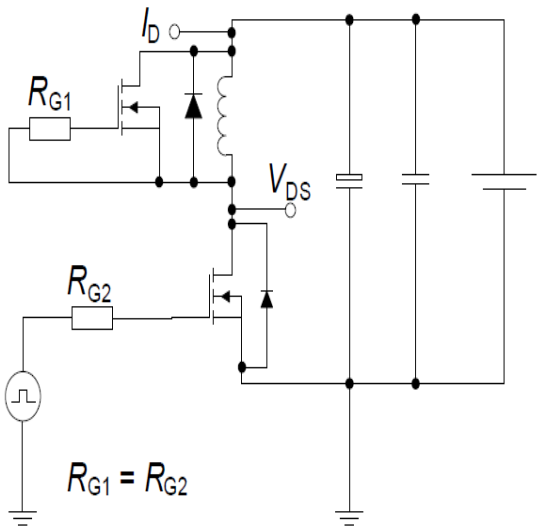
Unclamped inductive waveform



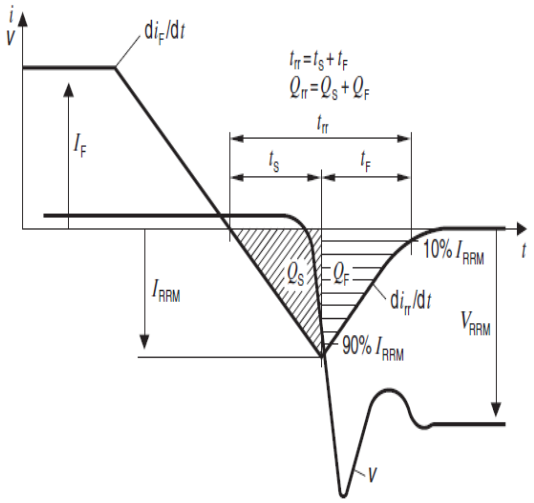
Test circuits

Test circuit and waveform for diode characteristics

Test circuit for diode characteristics

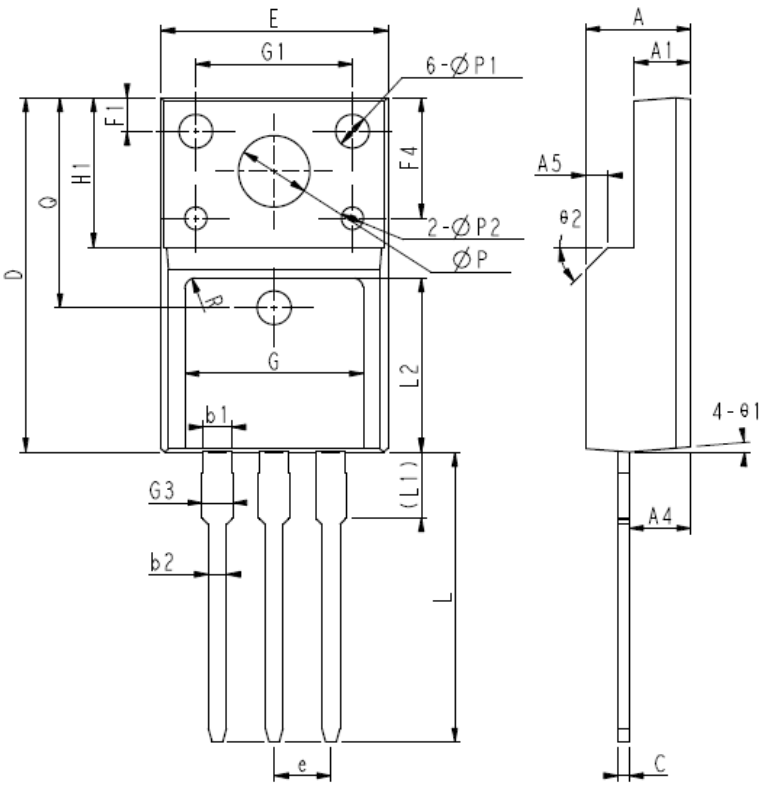


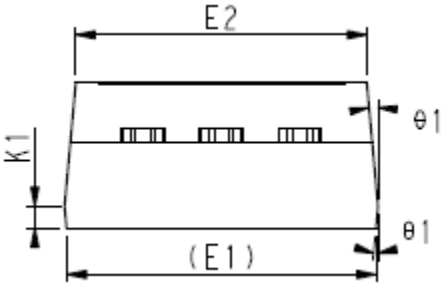
Diode recovery waveform



Package Outline

TO-220 Full PAK



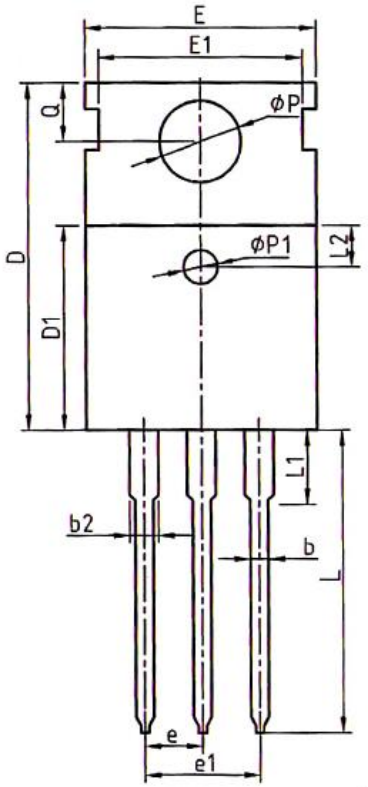


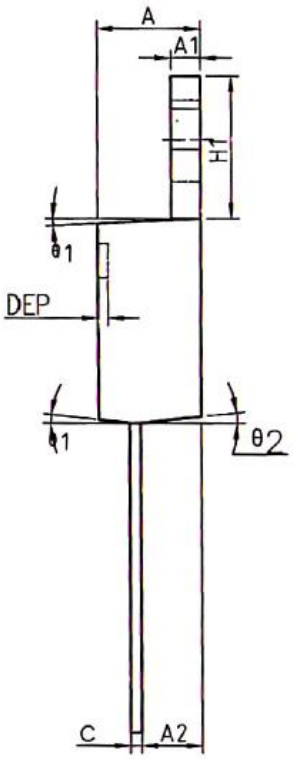
COMMON DIMENSIONS

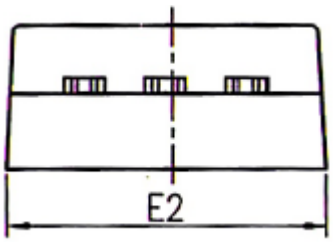
SYMBOL	MM		
	MIN	NOM	MAX
E	10.00	10.16	10.32
E1	9.94	10.04	10.14
E2	9.36	9.46	9.56
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A4	2.66	2.76	2.86
A5		1.00REF	
c	0.45	0.50	0.60
D	15.67	15.87	16.07
Q		9.40REF	
H1		6.70REF	
e		2.54BSC	
ΦP		3.18REF	
L	12.78	12.98	13.18
L1	2.83	2.93	3.03
L2	7.70	7.80	7.90
ΦP1	1.40	1.50	1.60
ΦP2	0.95	1.00	1.05
ΦP3		3.45REF	
θ1	3°	5°	7°
θ2	-	45°	-
F1	1.00	1.50	2.00
F2	13.80	13.90	14.00
F3	3.20	3.30	3.40
F4	5.30	5.40	5.50
G	7.80	8.00	8.20
G1	6.90	7.00	7.10
G3	1.25	1.35	1.45
b1	1.23	1.28	1.38
b2	0.75	0.80	0.90
K1	0.65	0.70	0.75
R		0.50REF	

Package Outline

TO-220





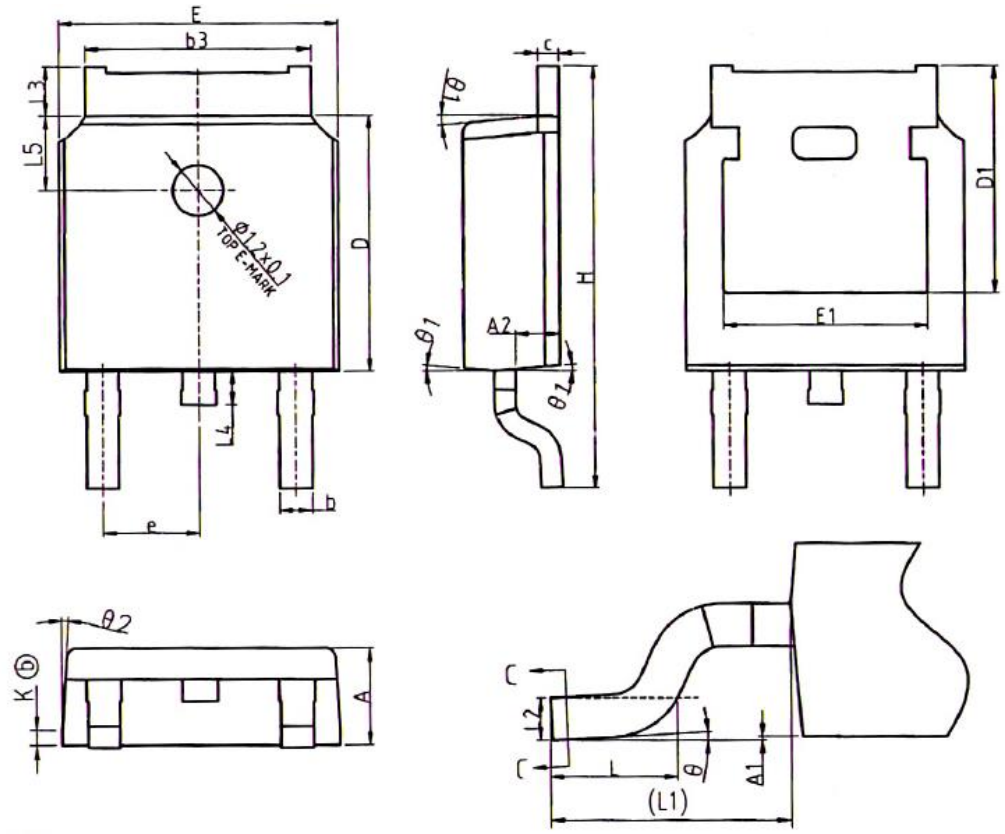


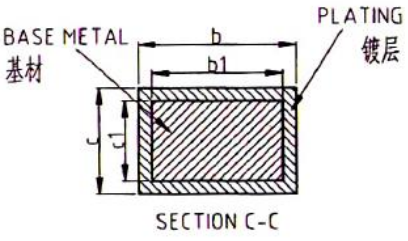
COMMON DIMENIONS

SYMBOL	MM		
	MIN	NOM	MAX
A	4.40	4.57	4.70
A1	1.27	1.30	1.37
A2	2.35	2.40	2.50
b	0.77	0.80	0.90
b2	1.17	1.27	1.36
c	0.48	0.50	0.56
D	15.40	15.60	15.80
D1	9.00	9.10	9.20
DEP	0.05	0.10	0.20
E	9.80	10.00	10.20
E1	–	8.70	–
E2	9.80	10.00	10.20
ΦP1	1.40	1.50	1.60
e	2.54BSC		
e1	5.08BSC		
H1	6.40	6.50	6.60
L	12.75	13.50	13.65
L1	–	3.10	3.30
L2		2.50REF	
ΦP	3.50	3.60	3.63
Q	2.73	2.80	2.87
θ1	5°	7°	9°
θ2	1°	3°	5°
θ3	1°	3°	5°

Package Outline

TO-252



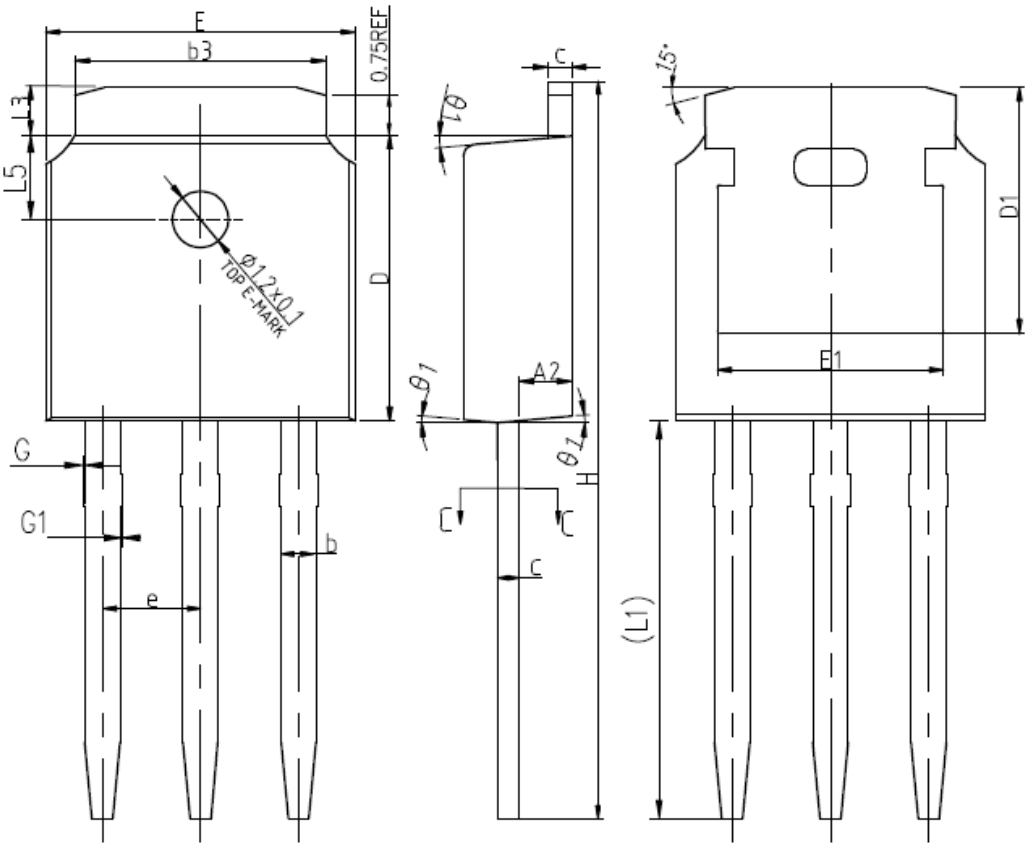


COMMON DIMENSIONS

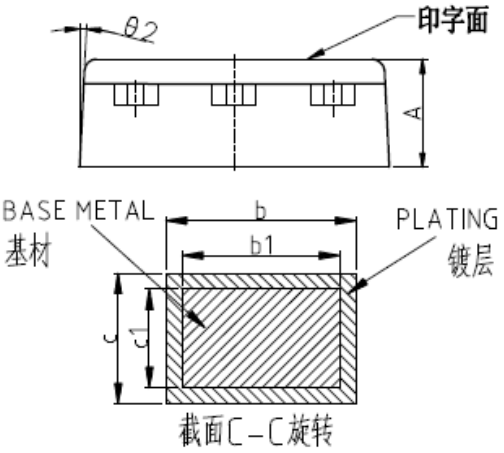
SYMBOL	MM		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0.00	-	0.10
A2	0.97	1.07	1.17
b	0.72	0.78	0.85
b1	0.71	0.76	0.81
b3	5.23	5.33	5.46
c	0.47	0.53	0.58
c1	0.46	0.51	0.56
D	6.00	6.10	6.20
D1		5.30REF	
E	6.50	6.60	6.70
E1	4.70	4.83	4.92
e		2.286BSC	
H	9.90	10.10	10.30
L	1.40	1.50	1.70
L1		2.90REF	
L2		0.51BSC	
L3	0.90	-	1.25
L4	0.60	0.80	1.00
L5	1.70	1.80	1.90
θ	0°	-	8°
θ1	5°	7°	9°
θ2	5°	7°	9°
K		0.40REF	

Package Outline

TO-251



COMMON DIMENSIONS



SYMBOL	MM		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A2	0.97	1.07	1.17
b	0.72	0.78	0.85
b1	0.71	0.76	0.81
b3	5.23	5.33	5.46
c	0.47	0.53	0.58
c1	0.46	0.51	0.56
D	6.00	6.10	6.20
D1		5.30REF	
E	6.50	6.60	6.70
E1	4.70	4.83	4.92
e		2.286BSC	
H	16.10	16.40	16.60
L1	9.20	9.40	9.60
L3	0.90	1.02	1.25
L5	1.70	1.80	1.90
θ1	5°	7°	9°
θ2	5°	7°	9°

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